

## Certificate of Compliance

DUNS		Document Date	URL for Additional Information
00-489-5751		Fri, May 18, 2012 07:30 PM	<a href="http://Fairchildsemi.com">Fairchildsemi.com</a>
Contact	Title	Phone	Email
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### Material Declaration Processing Information

FSID	Material Declaration	Site Owner	Assembly Location	Package Weight(g)	MSL Rating
FSBB15CH60	SPM27-CA	SUZHOU	INTERNAL SUZHOU	17.342	Not Applicable
Terminal Finish	Base Alloy	Green Status	Reflow Cycles	Max Time at Temp	Peak Temp
Matte Tin (Sn)	CU Alloy		Not Applicable		

### Homogenous Material Composition Declaration

Component	Material	Weight of Component(mg)	Substance	Weight (mg)	CAS	PPM in FSID
Chip	Other inorganic materials	67.700	Silicon	67.700	7440-21-3	3904
Die Attach	Other Organic Materials	0.495	Resin	0.074	54208-63-8	4
			Silver	0.421	7440-22-4	24
Die Attach Soft Solder	Other Nonferrous metals & alloys	31.399	Copper	0.157	7440-50-8	9
			Silver	0.942	7440-22-4	54
			Tin	30.300	7440-31-5	1747
Die Attach Solder		9.700	Silver	0.243	7440-22-4	14
			Tin	0.485	7440-31-5	28
			Lead	8.973	7439-92-1	517
Encapsulation	Thermoplastics	10122.000	Antimony Trioxide	101.000	1309-64-4	5824
			Bromine Resin	101.000	6386-73-8	5824
			Epoxy Resin	1010.000	29690-82-2	58239
			Silica	8910.000	60676-86-0	513770
Heat Sink	Ceramics / Glass	2720.000	Aluminum Oxide	980.016	1344-28-1	56510
			Copper	1739.984	7440-50-8	100331
Lead Frame	Other Ferrous alloys, non-stainless steels	4318.380	Silver	1.470	7440-22-4	85
			Phosphorus	1.730	7723-14-0	100
			Iron	5.180	7439-89-6	299
			Copper	4310.000	7440-50-8	248524
Plating	Other Nonferrous metals & alloys	53.300	Tin	53.300	7440-31-5	3073
Wire Bond	Aluminum & its alloys	18.300	Gold	1.120	7440-57-5	65
			Aluminum	18.300	7429-90-5	1055
	Precious metals	1.120	Gold	1.120	7440-57-5	65
			Aluminum	18.300	7429-90-5	1055

Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification.

Additionally, the following should be noted:

- This statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.
- CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.

## RoHS Declaration

The European Parliament and of the Council on the Restriction of the use of Certain Hazardous Substances in Electrical and Electronic Equipment (RoHS) directive restricts the concentration of Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) to 0.1% (1000 PPM) and restricts the concentration of Cadmium (Cd) to 0.01% (100 PPM) in homogeneous materials of electronic products.

The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU of FSC is aware of the Courts annulment of the exemption of decabromodiphenyl ether (decaBDE) effective June 08, 2011. FSC products do not contain Decabromodiphenyl ether (decaBDE).

**Exemptions as declared for the directive are: 0**

## China RoHS

With the possible exception of lead, if applicable (refer to the RoHS Declaration statement above), this product and all homogeneous materials in the product comply with the China RoHS standard SJ/T 11363-2006.

## REACH Compliance

The Regulation (EC) No 1907/2006 of the European Parliament and of the Council of 18 December 2006 concerning the Registration, Evaluation, Authorization, and Restriction of Chemicals (REACH) entered into force on June 1, 2007. Fairchild Semiconductor is aware of and agrees with the purpose of REACH which is to ensure a high level of protection of human health and the environment. Fairchild Semiconductor is compliant with all applicable requirements of REACH and has provided information regarding the chemical composition of our product(s) in this document.

Fairchild Semiconductor is neither a manufacturer nor importer of preparations into Europe and therefore the registration requirements do not apply to us. It is expected that any electronic materials manufacturers that use preparations from Europe in their products will ensure compliance with REACH registration requirements.

Product (articles) manufacturers or importers into Europe are obligated under Article 33 of REACH to inform recipients of any articles that contain chemicals on the Substances of Very High Concern (SVHC) candidate list above a 0.1% concentration (by weight per article). Products manufactured and marketed by Fairchild Semiconductor **do not** contain substances on the REACH SVHC candidate list in concentrations greater than 0.1% by weight per article.

Fairchild will continue to monitor the developments of the REACH legislation and is committed to meeting our responsibilities as an environmentally-responsible company. Refer to the ECHA European Chemical Agency weblink for a complete list of SVHC.  
[ECHA European Chemical Agency](#)

## Joint Industry Guide (JIG) 101

With the exception of RoHS exemptions listed above (if applicable), this product does not contain any restricted substances listed in the Joint Industry Guide (JIG) 101 in concentrations greater than the threshold listed.

Substance Name	Threshold
Asbestos	Intentionally added
Certain Azocolourants and Azodyes	Intentionally added
Cadmium / Cadmium Compounds	75 Ppm or Intentionally added
Hexavalent Chromium / Hexavalent Chromium Compounds	1000 ppm or intentionally added
Lead / Lead Compounds	1000 ppm or intentionally added
Mercury / Mercury Coumpounds	1000 ppm or intentionally added
Ozone Depleting substances (CFCs, HCFCs, HBFCs, carbon tetrachloride)	Class I: Intentionally added Class I: HCFCs 1000 ppm
Polybrominated Biphenyls (PBBs)	1000 ppm or intentionally added
Polybrominated Diphenylethers (PBDEs)	1000 ppm or intentionally added
Polychlorinated Biphenyl's (PCBs)	1000 ppm or intentionally added
Polychlorinated Naphthalenes (more than 3 chlorine atoms)	Intentionally added
Radioactive substances	Intentionally added
Certain Shortchain Chloronated Pataffins	Intentionally added
Tributyl Tin (TBT) and Triphenyl Tin (TPT)	Intentionally added
Tributyl Tin Oxide (TBTO)	Intentionally added

[Joint Industry Guide \(JIG\) 101](#)

The signature below is of the Company's designated personnel with delegated product ecology compliance responsibility and verifies that to the best of our knowledge the statements above are valid and accurate.

**David Lancaster**



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**Environmental Declaration**

The content of this document is based upon information collected from Fairchild Semiconductor's supply chain, manufacturing facilities and affiliates worldwide. Providing for limitations below, Fairchild Semiconductor certifies that the information provided in this document is correct as of the date indicated on this page.

Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.